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U.S. Department of Commerce, Patent and Trademark Office					Atty Docke	t No.	Serial No.			
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APR 2 6 200	<u> </u>		Filing Date		Group					
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*Examiner	1	Document	<u> </u>	T			Filing I			
Initial		Number	Date	Name	Class	Subclass	If Appro	priate		
20	AA	6,376,877	April 2002	Yu et al.						
28	AB	6,448,606	Sept. 2002	Yu et al.						
. 7/	AC	6,417,047	July 2002	Isobe						
w	AD	6,555,427	April 2003	Shimizu						
	AE									
	AF									
-	AG									
	AH	 		1						
	AI				+	-	_			
		<u>!</u>	Foreig	n Patent Documents						
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•		Document	Date	Country	Class	Subclass	Yes	No		
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		OTHER	ART (Including	Author, Title, Date, Po	ertinent Pages	Etc.)				
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*EXAMINER	: Initial if	f reference consid	ered, whether or n	not citation is in confo	rmance with N	IPEP 609; Drav	v line through			
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U.S. Department of Commerce, Patent and Trademark Office						Docket N	Serial No.				
					M-1	5210 US	10/678,317				
DEFORMATION DISCLOSURE STATEMENT BY APPLICANT						Applicant(s)					
(Use several sheets if necessary)						Yi Ding					
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TAY BADEA			U.S. I	Patent Documents			7				
*Examiner		Document Number	Deta	Date Name		Class Subclass		Filing Date If Appropriate			
Initial	AA	6,222,225	Date 24 Apr. 2001	Nakamura et al.		Class	Suociass	п Аррго	priace		
1	AB	6,228,713	8 May 2001	Pradeep et al.							
	AC	6,323,085	27 Nov. 2001	Sandhu et al.							
- 	AD	5,940,717	17 Aug. 1999	Rengarajan et al.		-					
	 	6,127,215	3 Oct 2000	Joachim et al.							
	AE	 	10 Oct. 2000	Chen				1			
	AF	6,130,129		Chem		•		-			
	AG	6,200,856	13 Mar. 2001						-		
	AH	6,319,794	20 Nov. 2001	Akatsu et al.							
	AI	6,355,524	12 Mar. 2002	Tuan et al.				<u> </u>			
W	AJ	6,518,618	11 Feb. 2003	Fazio et al.							
			Foreign	Patent Documents	<u>.</u>						
	· _[т							ıslatic		
	ļ	Document	Date	Country		Class	Subclass	Yes	N ₁		
<i>W</i>	AK	2000-174242	23 Jun. 2000	Љ							
	 			uthor, Title, Date, Pe			-				
W	AL	Aritome, S. et al., "A 0.67um ² Self-Aligned Shallow Trench Isolation Cell (SA-STI Cell) For 3V-only 256Mbit NAND EEPROMs," International Electron Devices meeting 1994, San Francisco, CA, December 11-14, 1994, pages 94-61 – 94-64.									
	AM	Keeney, Stephen N., "A 130nm Generation High Density Etox™ Flash Memory Technology, Intel, Corporation, Santa Clara, California, USA, 42 sheets.									
	AN	United States Patent Application No. 10/266,378 entitled "Floating Gate Memory Structures And Fabrication Methods," filed on October 7, 2002, Inventor: Chia-Shun Hsiao, Attorney Docket No. M-12200 US.									
	AO	United States Patent Application No. 10/262,785, entitled "Floating Gate Memory Fabrication Methods Comprising A Field Dielectric Etch With A Horizontal Etch Component," filed on October 1, 2002, Inventor: Yi Ding, Attorney Docket No.: M-12841 US.									
	AP	Silicon, Flash and Other Non-Volatile Memory Technologies, http://www.intel.com/research/silicon/flash.htm , September 12, 2002, pages 1-4.									
W	AQ	Patent Abstracts of	of Japan of JP 200	00-174242.							
Examiner	10	most	Date Considere	ed 5/24/64							